

ENGINEERING DEPT.		PRODUCT SPECIFICATION For 2.00 mm (.079") Pin Header of System CH74	SPEC.NO.: SPCH022C
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1. SCOPE:

This specification contains the test requirement of subject pin headers when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
EIA-364	Test methods for electrical connectors
JIS - C - 5402	Methods for test of connectors for electronic equipment
UL 94	Test for flammability of plastic materials for parts in devices and appliance

3. APPLICABLE SERIES NO.: **CH74 SERIES**

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

(P.C. Board on which the Pin Header are installed), 0.8 mm (.031") ~ 1.6 mm (.063")

REVIEWED : Eisley APPROVED : Sun VERIFIED : Michelle.

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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 100 mA max	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 1000 V 1minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 1000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Pin retention force	Push pin from insulator base at speed 25± 3 mm per minute	0.8 Kgf (7.84N)

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Solder ability	Soldering time: 5 ± 0.5 second Soldering pot: 245 ± 5°C	Minimum: 90% of immersed area
9.2	Resistance to soldering heat	Max. Infrared Reflow Soldering temperature & time: 230°C for 60 Sec. 260°C for 10 Sec.	No damage
9.3	Heat aging	105± 2°C, 96 hours	No damage
9.4	Humidity	40± 2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.5	Temperature cycling	One cycle consists of : (1)-55 ⁺⁰ ₋₃ °C , 30 min. (2)Room temp. 10-15 min. (3) 85 ⁺³ ₋₀ °C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial

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	ITEM	TEST CONDITION	REQUIREMENT
9.6	Salt spray	<p>Temperature: $35 \pm 3^{\circ}\text{C}$</p> <p>Solution: $5 \pm 1\%$</p> <p>Spray time: 48 ± 4 hours (Stamping before plated)</p> <p>Spray time: 24 ± 4 hours (Stamping after plated)</p> <p>Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed.</p> <p>The specimens shall be suspended from the top using waxed twine, string or nylon thread.</p> <p>The test only define the plating area, without plating area (as copper cross section) will not be defined.</p> <p>(EIA 364-26B / MIL-STD-202 Method 101)</p>	<p>Appearance: No damage</p> <p>Contact resistance: Less than twice of initial</p>

10. AMBIENT TEMPERATURE RANGE:

-40 to + 105°C ; + 215°C intermittent (Vapor Phase Solder Reflow) for SMT type